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IGBT

FGAF40N60UFD

Ultrafast IGBT

General Description

Fairchild's UFD series of Insulated Gate Bipolar Transistors (IGBTs) provides low conduction and switching losses. The UFD series is designed for applications such as motor control and general inverters where high speed switching is a required feature.

Features

- High speed switching
- Low saturation voltage : $V_{CE(sat)} = 2.3 \text{ V} @ I_C = 20 \text{A}$
- · High input impedance
- CO-PAK, IGBT with FRD : t_{rr} = 50ns (typ.)

Applications

AC & DC motor controls, general purpose inverters, robotics, and servo controls.





GCE

Absolute Maximum Ratings $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Description		FGAF40N60UFD	Units	
V _{CES}	Collector-Emitter Voltage		600	V	
V _{GES}	Gate-Emitter Voltage		± 20	V	
	Collector Current	@ T _C = 25°C	40	А	
IC	Collector Current	@ T _C = 100°C	20	А	
I _{CM (1)}	Pulsed Collector Current		160	А	
I _F	Diode Continuous Forward Current	@ T _C = 100°C	15	А	
I _{FM}	Diode Maximum Forward Current		160	А	
P_{D}	Maximum Power Dissipation	@ T _C = 25°C	100	W	
	Maximum Power Dissipation	@ T _C = 100°C	40	W	
T _J	Operating Junction Temperature	-	-55 to +150	°C	
T _{stg}	Storage Temperature Range		-55 to +150	°C	
TL	Maximum Lead Temp. for Soldering Purposes, 1/8" from Case for 5 Seconds		300	°C	

Notes :

(1) Repetitive rating : Pulse width limited by max. junction temperature

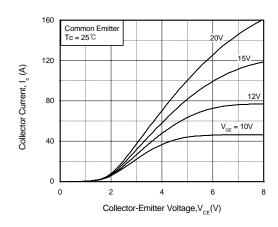
Thermal Characteristics

Symbol	Parameter	Тур.	Max.	Units
$R_{\theta JC}(IGBT)$	Thermal Resistance, Junction-to-Case		1.2	°C/W
$R_{\theta JC}(DIODE)$	Thermal Resistance, Junction-to-Case		2.6	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		40	°C/W

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Off Cha	racteristics					
BV _{CES}	Collector-Emitter Breakdown Voltage	$V_{GE} = 0V, I_{C} = 250uA$	600			V
ΔB _{VCES} / ΔT _J	Temperature Coefficient of Breakdown Voltage	V _{GE} = 0V, I _C = 1mA		0.6		V/°C
I _{CES}	Collector Cut-Off Current	$V_{CE} = V_{CES}, V_{GE} = 0V$			250	uA
I _{GES}	G-E Leakage Current	$V_{GE} = V_{GES}, V_{CE} = 0V$			± 100	nA
On Chai	racteristics					
V _{GE(th)}	G-E Threshold Voltage	$I_C = 20$ mA, $V_{CE} = V_{GE}$	3.5	5.1	6.5	V
	Collector to Emitter	$I_{C} = 20A$, $V_{GE} = 15V$		2.3	3.0	V
V _{CE(sat)}	Saturation Voltage	$I_C = 40A$, $V_{GE} = 15V$		3.1		V
•	c Characteristics	T.	1			
C _{ies}	Input Capacitance	$V_{CE} = 30V_{CE} = 0V_{CE}$		1075		pF
C _{oes}	Output Capacitance	- f = 1MHz		170		pF
C _{res}	Reverse Transfer Capacitance			50		pF
Switchir	ng Characteristics					
t _{d(on)}	Turn-On Delay Time			15		ns
t _r	Rise Time			30		ns
t _{d(off)}	Turn-Off Delay Time	$V_{CC} = 300 \text{ V}, I_{C} = 20 \text{A},$		65	130	ns
t _f	Fall Time	$R_G = 10\Omega, V_{GE} = 15V,$		35	100	ns
E _{on}	Turn-On Switching Loss	Inductive Load, T _C = 25°C		470		uJ
E _{off}	Turn-Off Switching Loss			130		uJ
E _{ts}	Total Switching Loss			600	1000	uJ
t _{d(on)}	Turn-On Delay Time			30		ns
t _r	Rise Time			37		ns
t _{d(off)}	Turn-Off Delay Time	$V_{CC} = 300 \text{ V}, I_{C} = 20\text{A},$		110	200	ns
t _f	Fall Time	$R_G = 10\Omega, V_{GE} = 15V,$		80	250	ns
E _{on}	Turn-On Switching Loss	Inductive Load, T _C = 125°C		500		uJ
E _{off}	Turn-Off Switching Loss			310		uJ
E _{ts}	Total Switching Loss			810	1200	uJ
Qg	Total Gate Charge	$V_{CE} = 300 \text{ V}, I_{C} = 20\text{A},$		77	150	nC
Q_{ge}	Gate-Emitter Charge	$V_{CE} = 300 \text{ V}, V_{C} = 20\text{A},$ - $V_{GF} = 15\text{V}$		20	30	nC
^	0-1-0-11-11-1	1 'GE 'V'	1	25	40	~^
Q _{gc}	Gate-Collector Charge Internal Emitter Inductance	Measured 5mm from PKG		25 14	40	nC nH

Electrical Characteristics of DIODE $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Conditions		Min.	Тур.	Max.	Units
\/	Diode Forward Voltage	I _F = 15A	$T_C = 25^{\circ}C$		1.4	1.7	V
V_{FM}			T _C = 100°C		1.3		
	Diode Reverse Recovery Time		$T_C = 25^{\circ}C$		50	95	nc
t _{rr}		I _F = 15A,	T _C = 100°C		74		ns
1	Diode Peak Reverse Recovery		$T_C = 25^{\circ}C$		4.5	6.0	Α
^I rr	Current	di/dt = 200A/us	T _C = 100°C		6.5		_ ^
Q _{rr}	Diode Reverse Recovery Charge		$T_C = 25^{\circ}C$		80	180	~C
			T _C = 100°C		220		nC



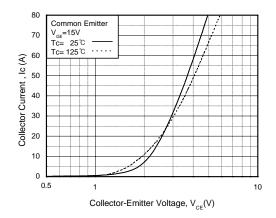
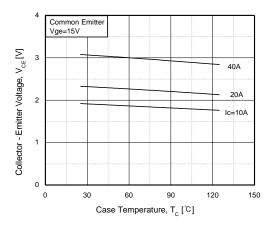


Fig 1. Typical Output Characteristics

Fig 2. Typical Saturation Voltage Characteristics



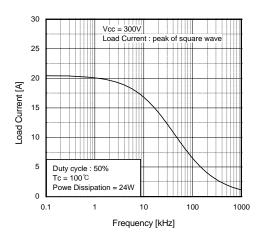
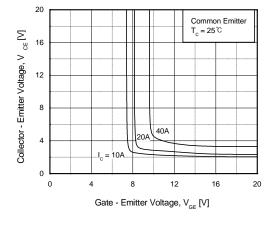


Fig 3. Saturation Voltage vs.

Case Temperature at Variant Current Level

Fig 4. Load Current vs. Frequency



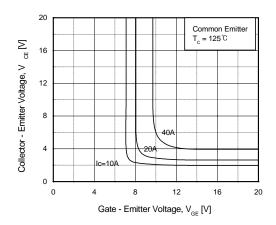
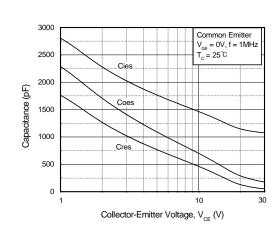


Fig 5. Saturation Voltage vs. V_{GE}

Fig 6. Saturation Voltage vs. V_{GE}

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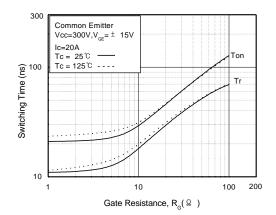
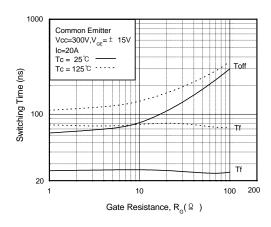


Fig 7. Capacitance Characteristics

Fig 8. Turn-On Characteristics vs.
Gate Resistance



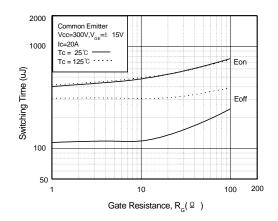
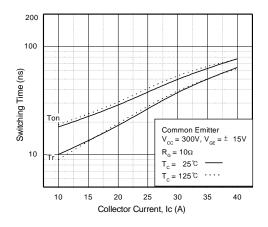


Fig 9. Turn-Off Characteristics vs.
Gate Resistance

Fig 10. Switching Loss vs. Gate Resistance



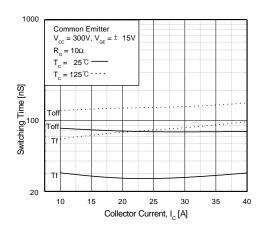
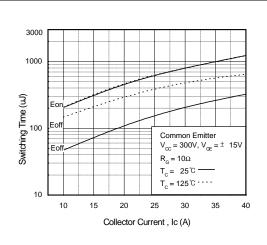


Fig 11. Turn-On Characteristics vs.
Collector Current

Fig 12. Turn-Off Characteristics vs.
Collector Current



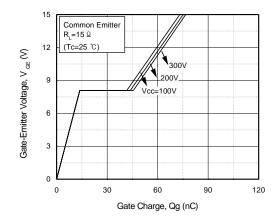
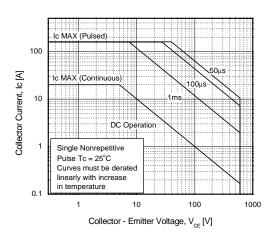


Fig 13. Switching Loss vs. Collector Current

Fig 14. Gate Charge Characteristics



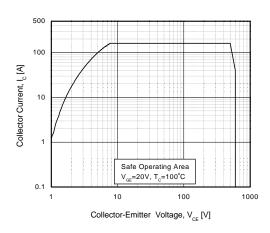


Fig 15. SOA Characteristics

Fig 16. Turn-Off SOA Characteristics

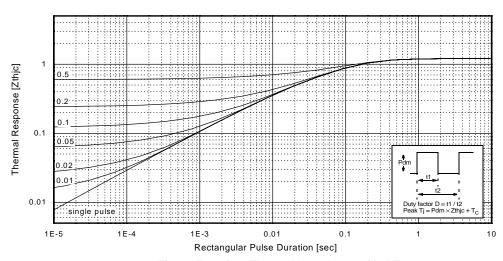
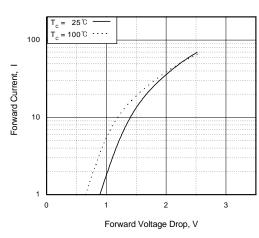


Fig 17. Transient Thermal Impedance of IGBT



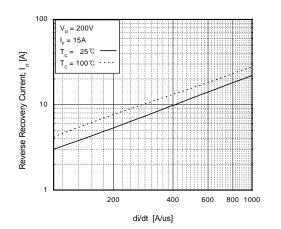
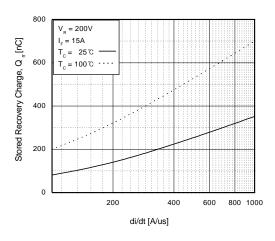


Fig 18. Forward Characteristics

Fig 19. Reverse Recovery Current



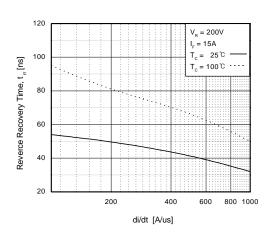
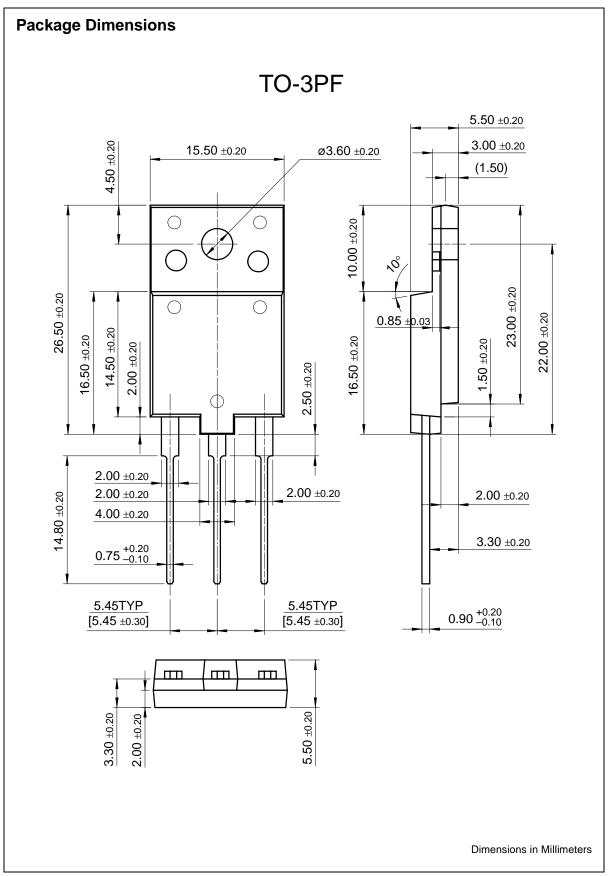


Fig 20. Stored Charge

Fig 21. Reverse Recovery Time



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